



**Shi Mao 毛适**

(+86) 13416342937  
maos19@mails.tsinghua.edu.cn  
Tsinghua University, Beijing, P.R. China



## Education

**M. Phil. @ Tsinghua University (THU)**

Fall 2019 –

Data Science & Information Technology, Tsinghua-Berkeley Shenzhen Institute (TBSI)

GPA: 3.98/4.0 Rank: 2<sup>nd</sup> /95

Excepted Graduation: 2022.06

**B. E. @ South China University of Technology (SCUT)**

Fall 2015 – Spring 2019

Intelligence Science & Technology, Automation Department

GPA: 3.88/4.0 Rank: 1<sup>st</sup> /51

**Visiting Student @ University of California, Berkely (UCB)**

Fall 2018

Computer Science & Statistics, Exchange Program

Got 3A and 1B+ in all major courses

## Research Experience

**GigaMVS: A Benchmark for Ultra-large-scale Gigapixel-level 3D Reconstruction** Sep 2020 – Oct 2021

Construct high-resolution 3D reconstruction dataset to support large scene reconstruction with fine details.

Contribute to the data collection and analysis. [Accepted by IEEE TPAMI](#) (as co-first-author).

**Surface Material Perception Through Multimodal Learning**

Aug 2021 – Apr 2022

Material perception using structured light camera by fusing reflecting, scattering and texture modalities.

Contribute to the methods, theoretical analysis and experiments. Under review by IEEE JSTSP (as first-author)

**Visual system of a BCI manipulator for automatic drinking**

Jun 2017– May 2018

Recognize and localize the cup for grasping by computer vision.

As a team leader of National Undergraduate Training Program. [Accepted by ROBIO](#). (as second author)

**Deciphering cortex neural signals using mesoscale imaging and electrophysiology**

Sep 2021 – Mar 2022

Analyze the dynamic yet distributed neural activities using imaging and electrophysiology methods.

Contribute to the neural decoding of facial expressions.

**Mapping brain dynamics in unconsciousness with a human SEEG resource**

Mar 2021 – Jun 2021

Characterized the neural oscillations of different consciousness state, based on SEEG implanted in human brain.

Contribute to the data analysis. Under review by Brain (as co-author).

## Honors

China National Scholarship (twice)

2016 & 2017

Mathematical Contest In Modeling (ICM)

Meritorious Award

2017

8-th Mathematics competition of Chinese College Students

First Price

2016